Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 8 with the following amended paragraph:

This invention relates in general to the ~~fields~~ field of vapor liquid delivery ~~system,~~ systems. More particularly, the present invention relates to a vapor liquid delivery system for a chemical vapor deposition (CVD) process.

Please replace the paragraph beginning at page 1, line 15 with the following amended paragraph:

The controlled deposition of thin organic and inorganic films is an important step in the manufacture of integrated circuits. These films are deposited to remain as an inherent part of the device structure, or to constitute intermediate layers that are used for particular processing steps and then removed. One of the methods for the deposition of thin films is a chemical vapor deposition (CVD).

Please replace the paragraph beginning at page 2, line 15 with the following amended paragraph:

In accordance with the present invention, a heating injection apparatus for a vapor liquid delivery system, one object of the present invention is an isolated liquid source from a reaction chamber efficiently and prevents to induce polymerization.

Please replace the paragraph beginning at page 3, line 15 with the following amended paragraph:

In accordance with the present invention, an inert gas purging part includes a liquid injector, a three-way valve, an exhausting branch and a purging nozzle. Liquid source resides in the front of a liquid injector, and this liquid source will be injected into a gas line through a liquid injector. The three-way valve ~~disposing~~ located between the liquid source and the liquid injector, and the three-way valve is used to control access of three pathways here and to isolate from process gases. One passageway of the three-way valve is connected to a purging gas that is used to purge out the liquid source remains in the liquid injector. The purging procedure is used

to purge the liquid source between the three-way valve and the liquid injector to prevent polymerization, and thus would improve ~~improving~~ machine uptime.

Please replace the paragraph beginning at page 4, line 7 with the following amended paragraph:

In accordance with the present invention, a ~~liquid~~ heating injection apparatus for a vapor liquid delivery system improves the previous disadvantages of prior art. The ~~liquid~~ heating injection apparatus of the present invention can continuously ~~purging~~ purge out the liquid source that remains inside the liquid injector to prevent polymerization. And the ~~liquid~~ heating injection apparatus of the present invention solves a short heating passage problem relate to can not provide enough time to heat process gases, which has a high potential to reduce the temperature of vapor and cause further condensation.

Please replace the paragraph beginning at page 5, line 11 with the following amended paragraph:

The present invention is a ~~liquid~~ heating injection apparatus for a vapor liquid delivery system, and this apparatus implements a thermostat device to heat process gases and an inert gas purging module used to isolate liquid source from other process gases.

Please replace the paragraph beginning at page 5, line 16 with the following amended paragraph:

In FIG. 2, shown a preferred embodiment of ~~liquid~~ heating inject apparatus of the present invention for a vapor liquid delivery system used. A liquid source 200, which resides in the front of liquid injector 205, the material of liquid source ~~material~~ in this preferred embodiment is TMCTS (1, 3, 5, 7, Tetramethylcyclotetrasiloxane~~)~~; $C_4H_{16}O_4Si_4$), in another embodiment, the liquid source can be another required materials. Liquid source 200 will be atomized to be an atomized liquid source 201, and then the atomized liquid source 201 is injected into gas line 245 by liquid injector 205. There is a first three-way valve 210 ~~disposing~~ located between the liquid source 200 and the liquid injector 205, and the first three-way valve 210 is used to control the access of the first three-way valve 210 and isolate from process gases.

Please replace the paragraph beginning at page 6, line 7 with the following amended paragraph:

In FIG.2, a branch 220 diverts to a pump 221. The branch 220 is used to stabilize pressure and the speed of vapor flow of the vapor liquid delivery system. And the branch 220 can also be used as an exhausting branch. A second three-way valve 240 connected to the exhausting branch 220, gas line 245 and delivery line 250. And the purging gas provider 230 made the liquid source 200 has no chance to come in contact with other reactive process gases to induce polymerization, due to the purging gas always flushes the gas line 245 and is diverted to pump via an exhausting branch 220. Purging procedures purges out the liquid source that remains ~~remaining~~ between the first three-way valve 210 and liquid injector 205, and then the exhausting branch 220 exhausts the ~~purged~~ purging gas. The purging procedure and other processes can be executed simultaneously and it would improve the machine uptime.

Please replace the paragraph beginning at page 6, line 21 with the following amended paragraph:

Continuously referring to FIG.2, a carrier gas 215 before entering the gas line 245 has been heated by a thermostat device 225. The carrier gas 215 is used to carry the atomized liquid source 201 that is injected by liquid injector 205, and then the carrier gas 215 delivers the atomized liquid source 201 pass through the delivery line 250 into gas-mixing device 255. The thermostat device 225 is used to heat the carrier gas 215 to the demanded production temperature before the carrier gas 215 enters the vapor liquid delivery system. The thermostat device 225 heats the gas more efficiently, quickly and holds the gas temperature constant. And the thermostat device 225 can also ~~maintains~~ maintain the temperature of vapor and prevent further condensation caused by a temperature decrease when the carrier gas 215 is mixed with atomized liquid source 201.

Please replace the paragraph beginning at page 7, line 7 with the following amended paragraph:

In this preferred embodiment of the present invention, the temperature of the carrier gas to carry the atomized liquid source TMCTS in the delivery line 250 at a temperature no less than 350°C, but not greater than 450°C, and the preferred temperature being 400°C. The heating source of thermostat device in this preferred embodiment of present invention can be heating coil

or an infrared ray thermostat device, and the temperature setting of the thermostat device can be adjusted to meet the demand production requirement. In other embodiment the thermostat device can be other adjustable heating apparatus.